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(54) Title: PLANARIZATION COMPOSITION FOR METAL SURFACES COMPRISING AN ALUMINA HYDRATE ABRASIVE

(57) Abstract: The present invention provides CMP abrasive slurry that is substantially free of aluminum oxide and comprises liquid and solids wherein the solids comprises: (a) in an amount of at least about 90 weight percent based on the solids, at least one non-spherical component having formula Al_2O_3-xH_2O where x ranges from 1 to 3; and (b) up to about one weight percent based on the solids portion of submicron alpha-alumina. The CMP abrasive slurry may be used to polish metallic or dielectric surfaces in computer wafers.